

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	AMG/16/9756	
1.3 Title of PCN	SO8 and SO8 exposed pad packaged products lead frame change in ST's subcontractor Amkor	
1.4 Product Category	See product list	
1.5 Issue date	2016-07-05	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Francesca Marta SANDRINI,Emanuele VAVASSORI,Marcello SAN BIAGIO
2.1.2 Marketing Manager	Vincenzo MONTEMEZZO,Carolina SELVA,Massimiliano MERISIO
2.1.3 Quality Manager	Jean-Marc BUGNARD,Alessandro PLATINI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), lead frame, resin, wire, ...)	AMKOR Philippines (ST's subcontractor)

4. Description of change

	Old	New
4.1 Description	Products in SO8 Exposed Pad and SO8 packages are assembled in Amkor using old Lead Frame Matrix (OMLF) and High Density Lead Frame (HDLF).	SO8 Exposed pad products will be moved to Ultra Density Lead Frame (UDLF). SO8 products will be moved to Xtreme Density Lead Frame (XDLF).
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact on form, fit, function, reliability, or processability	

5. Reason / motivation for change

5.1 Motivation	The purpose of the change from ODLF/HDLF to UDLF/XDLF production format is to enhance the manufacturing process for higher volume production with greater efficiency and productivity.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Finish good codes
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7. Timing / schedule

7.1 Date of qualification results	2016-04-30
7.2 Intended start of delivery	2016-09-22
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	9756_Qualif report.zip		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2016-07-05

9. Attachments (additional documentations)

9756PpPrdtLst.pdf
2_PCN9756_SO8_SO8EXPAD Strip_Lead Frame change to XD_UD in Amkor.pdf
9756_Qualif report.zip

10. Affected parts

10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
L5970D	L5970D	
L5970D013TR	L5970D013TR	
L5973AD	L5973AD	
L5973ADTR	L5973ADTR	
L5973D	L5973D	
L5973D013TR	L5973D013TR	
	L5987ATR	
	L6932H1.2TR	
	L7980A	
	L7980ATR	
	L7981A	
	L7981ATR	
	L7985A	
	L7985ATR	
	L7986A	
	L7986ATR	
	L7986TA	
	LED2001PHR	
	LED5000PHR	
	SRK2000A	
	SRK2000ATR	
	SRK2000DTR	
	ST1S10PHR	
	ST1S14PHR	
	ST1S40IPHR	
	ST1S41PHR	
	STCS1APHR	
	STCS1PHR	



Public Products List

PCN Title : SO8 and SO8 exposed pad packaged products lead frame change in ST's subcontractor Amkor

PCN Reference : AMG/16/9756

PCN Created on : 18-Apr-2016

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

L7985A	ST1S40IPHR	L5973ADTR
ST1S10PHR	L7980A	L7986A
L7985ATR	L7986ATR	L7980ATR
SRK2000D	L5986A	L5973D013TR
LED2001PHR	L7981ATR	SRK2000DTR
L5987ATR	L5973D	STCS1PHR
L7981A	L7986TATR	ST1S14PHR
L7986TA	L5986ATR	L5973AD
L5970D013TR	L5970D	STCS1APHR
SRK2000A	LED5000PHR	L5987A
SRK2000ATR	L6932H1.2	ST1S41PHR
L6932H1.2TR		



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